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While the invention has been illustrated and described as embodied in layer sequences built on substrates in thin-film technology, it is not intended to be limited to the details shown, since various modifications and changes may be made without departing in any way from the spirit of the present invention.

**In the Drawing:**

Please accept the appended sketch of figure 1 with changes marked in red. Approval of the changes in Fig. 1 and withdrawal of the objection to the drawing is respectfully requested.

**In the Abstract:**

Please replace ✓ the current abstract with the following amended or replacement abstract:

**ABSTRACT OF THE DISCLOSURE**

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The layer sequence built on a substrate in thin-film technology includes an electrically conductive sputtered layer and an electrically conductive reinforcing layer for reinforcing or strengthening the sputtered layer, which is applied on the sputtered layer by a method other than sputtering. In order to remove conducting material from the conductive layers with the aid of a laser for the purposes of adjustment while producing as little contaminating material as possible, the electrically conductive reinforcing layer has a reduced thickness or is completely eliminated in regions of the electrically conductive layers to be adjusted than in other regions outside of the regions to be adjusted.